

Welcome to [E-XFL.COM](https://www.e-xfl.com)

Embedded - Microcontrollers - Application Specific: Tailored Solutions for Precision and Performance

Embedded - Microcontrollers - Application Specific represents a category of microcontrollers designed with unique features and capabilities tailored to specific application needs. Unlike general-purpose microcontrollers, application-specific microcontrollers are optimized for particular tasks, offering enhanced performance, efficiency, and functionality to meet the demands of specialized applications.

What Are Embedded - Microcontrollers - Application Specific?

Application specific microcontrollers are engineered to

Details

Product Status	Not For New Designs
Applications	Automotive
Core Processor	ARM® Cortex®-M3
Program Memory Type	FLASH (128kB)
Controller Series	-
RAM Size	6K x 8
Interface	LIN, SSI, UART
Number of I/O	10
Voltage - Supply	5.5V ~ 28V
Operating Temperature	-40°C ~ 150°C
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	PG-VQFN-48-29
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/tle9879qxa20xuma1

21	High-Speed Synchronous Serial Interface (SSC1/SSC2)	65
21.1	Features	65
21.2	Introduction	66
21.2.1	Block Diagram	66
22	Measurement Unit	67
22.1	Features	67
22.2	Introduction	67
22.2.1	Block Diagram	68
22.2.1.1	Block Diagram BEMF Comparator	69
23	Measurement Core Module (incl. ADC2)	70
23.1	Features	70
23.2	Introduction	70
23.2.1	Block Diagram	70
23.2.2	Measurement Core Module Modes Overview	71
24	10-Bit Analog Digital Converter (ADC1)	72
24.1	Features	72
24.2	Introduction	72
24.2.1	Block Diagram	73
25	High-Voltage Monitor Input	74
25.1	Features	74
25.2	Introduction	74
25.2.1	Block Diagram	74
26	Bridge Driver (incl. Charge Pump)	75
26.1	Features	75
26.2	Introduction	75
26.2.1	Block Diagram	76
26.2.2	General	76
27	Current Sense Amplifier	77
27.1	Features	77
27.2	Introduction	77
27.2.1	Block Diagram	77
28	Application Information	78
28.1	BLDC Driver	78
28.2	ESD Immunity According to IEC61000-4-2	80
29	Electrical Characteristics	81
29.1	General Characteristics	81
29.1.1	Absolute Maximum Ratings	81
29.1.2	Functional Range	84
29.1.3	Current Consumption	85
29.1.4	Thermal Resistance	87
29.1.5	Timing Characteristics	87
29.2	Power Management Unit (PMU)	88
29.2.1	PMU I/O Supply (VDDP) Parameters	88
29.2.2	PMU Core Supply (VDDC) Parameters	90
29.2.3	VDDEXT Voltage Regulator (5.0V) Parameters	91
29.2.4	VPRE Voltage Regulator (PMU Subblock) Parameters	93
29.2.4.1	Load Sharing Scenarios of VPRE Regulator	93
29.2.5	Power Down Voltage Regulator (PMU Subblock) Parameters	94

3.2 Pin Configuration

After reset, all pins are configured as input (except supply and LIN pins) with one of the following settings:

- Pull-up device enabled only (PU)
- Pull-down device enabled only (PD)
- Input with both pull-up and pull-down devices disabled (I)
- Output with output stage deactivated = high impedance state (Hi-Z)

The functions and default states of the TLE9879QXA20 external pins are provided in the following table.

Type: indicates the pin type.

- I/O: Input or output
- I: Input only
- O: Output only
- P: Power supply

Not all alternate functions listed.

Table 2 Pin Definitions and Functions

Symbol	Pin Number	Type	Reset State ¹⁾	Function
P0				Port 0 Port 0 is a 5-bit bidirectional general purpose I/O port. Alternate functions can be assigned and are listed in the port description. Main function is listed below.
P0.0	21	I/O	I/PU	SWD Serial Wire Debug Clock
P0.1	23	I/O	I/PU	GPIO General Purpose IO Alternate function mapping see Table 8
P0.2	25	I/O	I/PD	GPIO General Purpose IO Alternate function mapping see Table 8 <i>Note: For a functional SWD connection this GPIO must be tied to zero!</i>
P0.3	24	I/O	I/PU	GPIO General Purpose IO Alternate function mapping see Table 8
P0.4	18	I/O	I/PD	GPIO General Purpose IO Alternate function mapping see Table 8
P1				Port 1 Port 1 is a 5-bit bidirectional general purpose I/O port. Alternate functions can be assigned and are listed in the Port description. The principal functions are listed below.
P1.0	15	I/O	I	GPIO General Purpose IO Alternate function mapping see Table 9
P1.1	16	I/O	I	GPIO General Purpose IO Alternate function mapping see Table 9
P1.2	17	I/O	I	GPIO General Purpose IO Alternate function mapping see Table 9
P1.3	26	I/O	I	GPIO General Purpose IO, used for Inrush Transistor Alternate function mapping see Table 9
P1.4	27	I/O	I	GPIO General Purpose IO Alternate function mapping see Table 9

5.2.1 Block Diagram

The following figure shows the structure of the Power Management Unit. **Table 4** describes the submodules in more detail.



Figure 3 Power Management Unit Block Diagram

Table 4 Description of PMU Submodules

Mod. Name	Modules	Functions
Power Down Supply	Independent supply voltage generation for PMU	This supply is dedicated to the PMU to ensure an independent operation from generated power supplies (VDDP, VDDC).
LP_CLK (= 18 MHz)	- Clock source for all PMU submodules - Backup clock source for System - Clock source for WDT1	This ultra low power oscillator generates the clock for the PMU. This clock is also used as backup clock for the system in case of PLL Clock failure and as an independent clock source for WDT1.
LP_CLK2 (= 100 kHz)	Clock source for PMU	This ultra low power oscillator generates the clock for the PMU in Stop Mode and in the cyclic modes.
Peripherals	Peripheral blocks of PMU	These blocks include the analog peripherals to ensure a stable and fail-safe PMU startup and operation (bandgap, bias).

6.2.1 Block Diagram

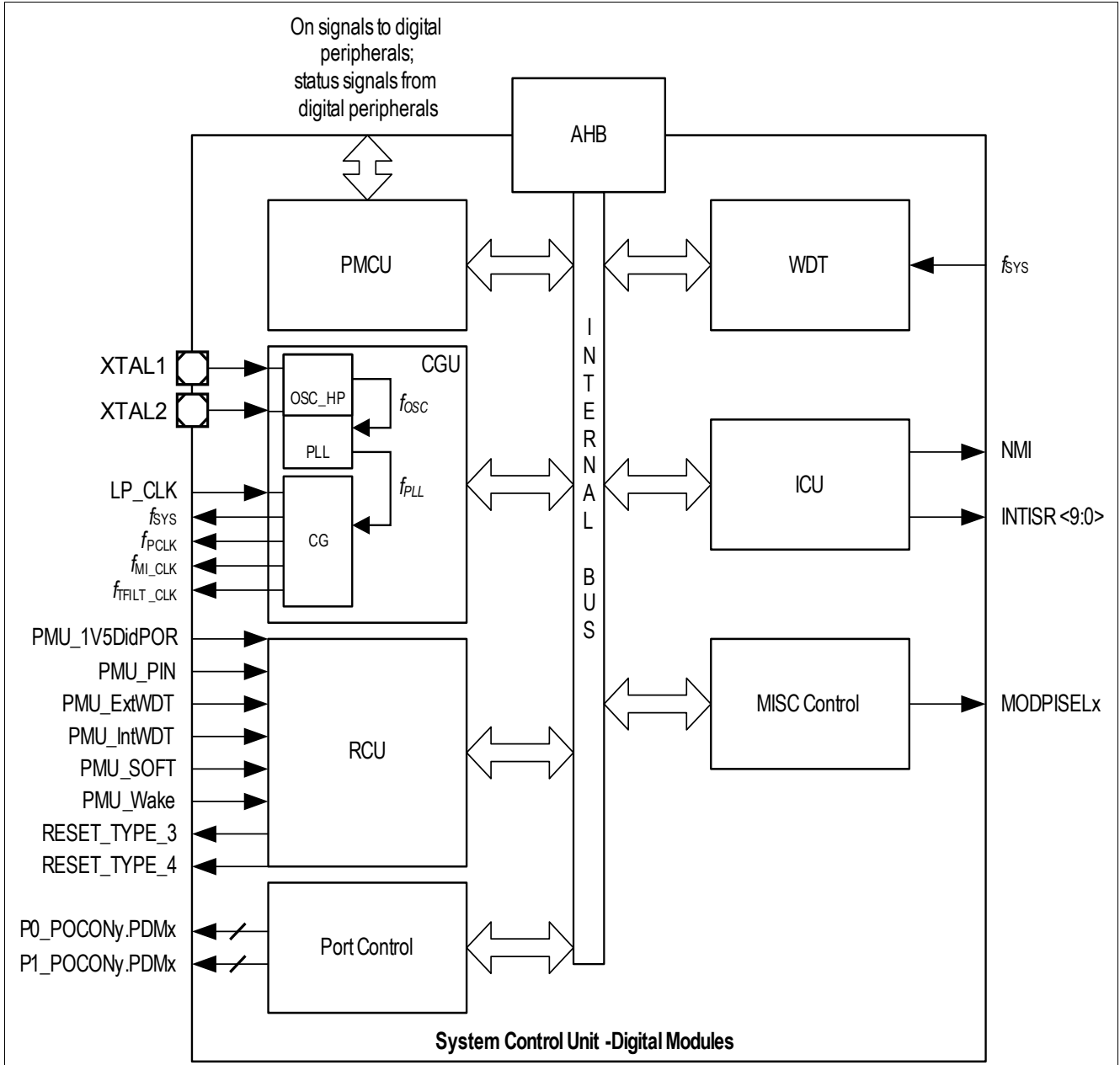


Figure 8 System Control Unit - Digital Modules Block Diagram

AHB (Advanced High-Performance Bus)

PMCU (Power Module Control Unit)

WDT (Watchdog Timer in SCU-DM)

- f_{SYS} System clock

CGU (Clock Generation Unit)

- f_{SYS} System clock
- f_{PCLK} Peripheral clock

Table 5 External CAP Capacitors

Fundamental Mode Crystal Frequency (approx., MHz)	Load Caps C_1, C_2 (pF)
4	33
8	18
12	12
16	10
20	10
25	8

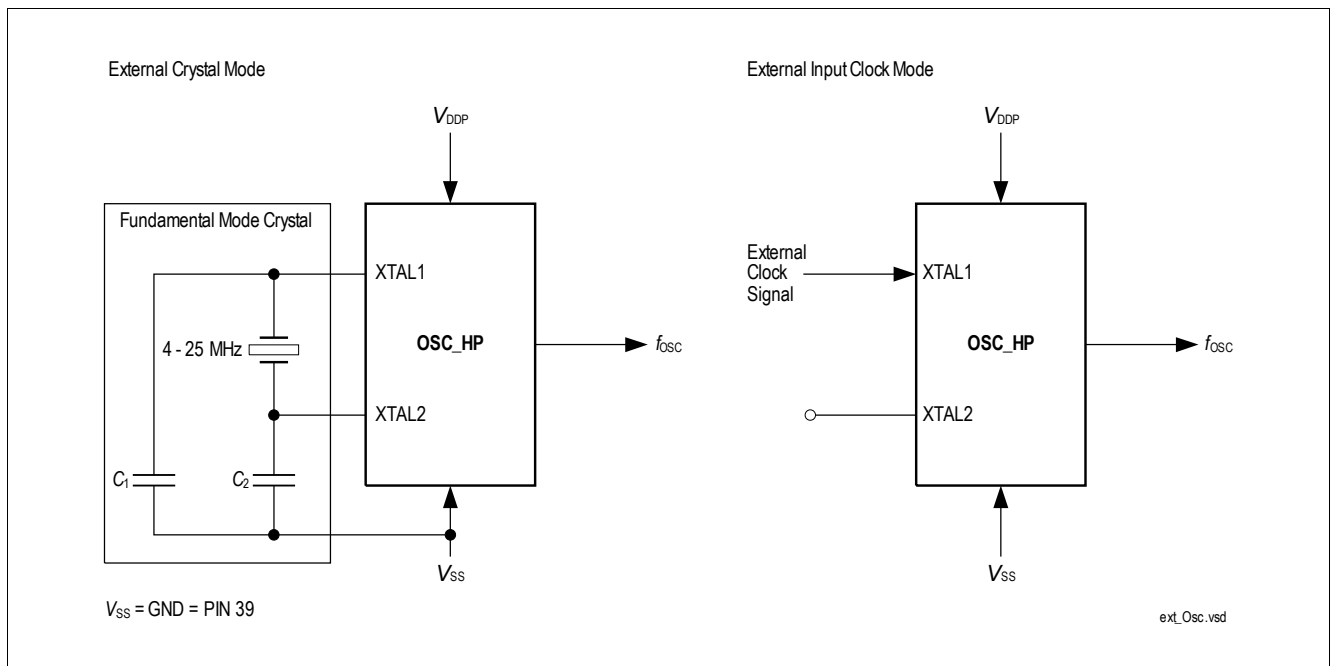


Figure 10 TLE9879QXA20 External Circuitry for the OSC_HP

10 Address Space Organization

The TLE9879QXA20 manipulates operands in the following memory spaces:

- 128 KByte of Flash memory in code space
- 32 KByte Boot ROM memory in code space (used for boot code and IP storage)
- 6 KByte RAM memory in code space and data space (RAM can be read/written as program memory or external data memory)
- Special function registers (SFRs) in peripheral space

The figure below shows the detailed address alignment of TLE9879QXA20:

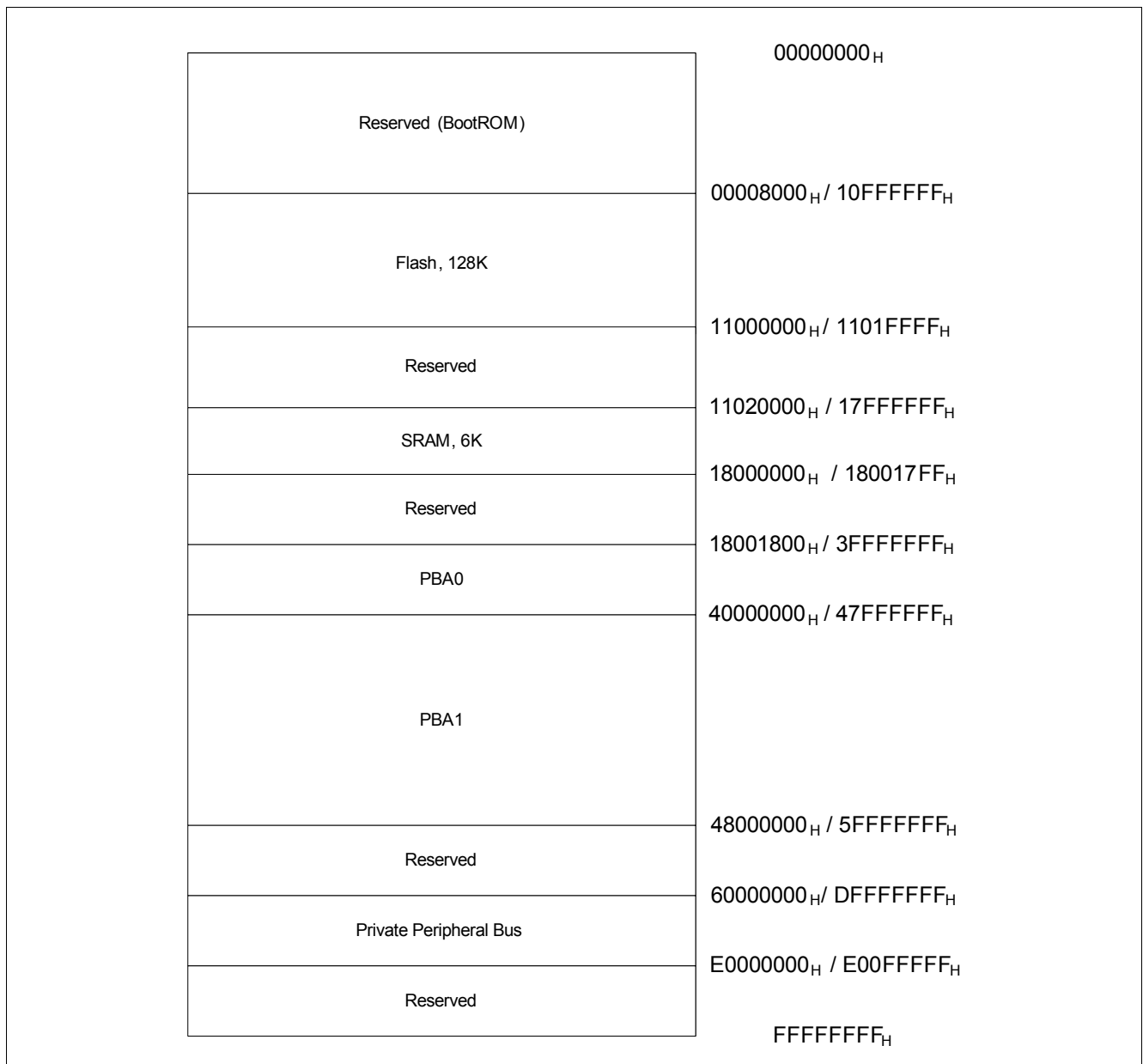


Figure 14 TLE9879QXA20 Memory Map

11.3 NVM Module (Flash Memory)

The Flash Memory provides an embedded user-programmable non-volatile memory, allowing fast and reliable storage of user code and data.

Features

- In-system programming via LIN (Flash Mode) and SWD
- Error Correction Code (ECC) for detection of single-bit and double-bit errors and dynamic correction of single Bit errors.
- Interrupts and signals double-bit error by NMI
- Program width of 128 byte (page)
- Minimum erase width of 128 bytes (page)
- Integrated hardware support for EEPROM emulation
- 8 byte read access
- Physical read access time: 75 ns
- Code read access acceleration integrated; read buffer and automatic pre-fetch
- Page program time: 3 ms
- Page erase (128 bytes) and sector erase (4K bytes) time: 4ms

Note: The user has to ensure that no flash operations which change the content of the flash get interrupted at any time.

The clock for the NVM is supplied with the system frequency f_{sys} . Integrated firmware routines are provided to erase NVM, and other operations including EEPROM emulation are provided as well.

12 Interrupt System

12.1 Features

- Up to 16 interrupt nodes for on-chip peripherals
- Up to 8 NMI nodes for critical system events
- Maximum flexibility for all 16 interrupt nodes

12.2 Introduction

Before enabling an interrupt, all corresponding interrupt status flags should be cleared.

12.2.1 Overview

The TLE9879QXA20 supports 16 interrupt vectors with 16 priority levels. Fifteen of these interrupt vectors are assigned to the on-chip peripherals: GPT12, SSC, CCU6, DMA, Bridge Driver and A/D Converter are each assigned to one dedicated interrupt vector; while UART1 and Timer2 or UART2, External Interrupt 2 and Timer21 share interrupt vectors. Two vectors are dedicated for External Interrupt 0 and 1.

Table 6 Interrupt Vector Table

Service Request	Node ID	Description
GPT12	0/1	GPT interrupt (T2-T6, CAPIN)
MU- ADC8/T3	2	Measurement Unit, VBG, Timer3, BEMF
ADC1	3	ADC1 interrupt / VREF5V Overload / VREF5V OV/UV, 10-bit ADC
CCU0	4	CCU6 node 0 interrupt
CCU1	5	CCU6 node 1 interrupt
CCU2	6	CCU6 node 2 interrupt
CCU3	7	CCU6 node 3 interrupt
SSC1	8	SSC1 interrupt (receive, transmit, error)
SSC2	9	SSC2 interrupt (receive, transmit, error)
UART1	10	UART1 (ASC-LIN) interrupt (receive, transmit), Timer2, linsync1, LIN
UART2	11	UART2 interrupt (receive, transmit), Timer21, External interrupt (EINT2)
EXINT0	12	External interrupt (EINT0), MON
EXINT1	13	External interrupt (EINT1)
BDRV/CP	14	Bridge Driver / Charge Pump
DMA	15	DMA Controller

Table 7 NMI Interrupt Table

Service Request	Node	Description
Watchdog Timer NMI	NMI	Watchdog Timer overflow
PLL NMI	NMI	PLL Loss-of-Lock
NVM Operation Complete NMI	NMI	NVM Operation Complete
Overtemperature NMI	NMI	System Overtemperature

14 GPIO Ports and Peripheral I/O

The TLE9879QXA20 has 15 port pins organized into three parallel ports: Port 0 (P0), Port 1 (P1) and Port 2 (P2). Each port pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. P0 and P1 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. On Port 2 (P2) analog inputs are shared with general purpose input.

14.1 Features

Bidirectional Port Features (P0, P1)

- Configurable pin direction
- Configurable pull-up/pull-down devices
- Configurable open drain mode
- Configurable drive strength
- Transfer of data through digital inputs and outputs (general purpose I/O)
- Alternate input/output for on-chip peripherals

Analog Port Features (P2)

- Configurable pull-up/pull-down devices
- Transfer of data through digital inputs
- Alternate inputs for on-chip peripherals

14.2 Introduction

14.2.1 Port 0 and Port 1

Figure 17 shows the block diagram of an TLE9879QXA20 bidirectional port pin. Each port pin is equipped with a number of control and data bits, thus enabling very flexible usage of the pin. By defining the contents of the control register, each individual pin can be configured as an input or an output. The user can also configure each pin as an open drain pin with or without internal pull-up/pull-down device.

Each bidirectional port pin can be configured for input or output operation. Switching between input and output mode is accomplished through the register `Px_DIR` ($x = 0$ or 1), which enables or disables the output and input drivers. A port pin can only be configured as either input or output mode at any one time.

In input mode (default after reset), the output driver is switched off (high-impedance). The voltage level present at the port pin is translated into a logic 0 or 1 via a Schmitt trigger device and can be read via the register `Px_DATA`.

In output mode, the output driver is activated and drives the value supplied through the multiplexer to the port pin. In the output driver, each port line can be switched to open drain mode or normal mode (push-pull mode) via the register `Px_OD`.

The output multiplexer in front of the output driver enables the port output function to be used for different purposes. If the pin is used for general purpose output, the multiplexer is switched by software to the data register `Px_DATA`. Software can set or clear the bit in `Px_DATA` and therefore directly influence the state of the port pin. If an on-chip peripheral uses the pin for output signals, alternate output lines (AltDataOut) can be switched via the multiplexer to the output driver circuitry. Selection of the alternate output function is defined in registers `Px_ALTSEL0` and `Px_ALTSEL1`. When a port pin is used as an alternate function, its direction must be set accordingly in the register `Px_DIR`.

14.3 TLE9879QXA20 Port Module

14.3.1 Port 0

14.3.1.1 Port 0 Functions

Table 8 Port 0 Input/Output Functions

Port Pin	Input/Output	Select	Connected Signal(s)	From/to Module
P0.0	Input	GPI	P0_DATA.P0	
		INP1	SWCLK / TCK_0	SW
		INP2	T12HR_0	CCU6
		INP3	T4INA	GPT12T4
		INP4	T2_0	Timer 2
		INP5	–	–
		INP6	EXINT2_3	SCU
	Output	GPO	P0_DATA.P0	
		ALT1	T3OUT	GPT12T3
		ALT2	EXF21_0	Timer 21
		ALT3	RXDO_2	UART2
P0.1	Input	GPI	P0_DATA.P1	
		INP2	T13HR_0	CCU6
		INP3	TxD1	LIN_TxD
		INP4	CAPINA	GPT12CAP
		INP5	T21_0	Timer 21
		INP6	T4INC	GPT12T4
		INP7	MRST_1_2	SSC1
		INP8	EXINT0_2	SCU
	Output	GPO	P0_DATA.P1	
		ALT1	TxD1	UART1 / LIN_TxD
		ALT2	–	–
		ALT3	T6OUT	GPT12T6

Table 8 Port 0 Input/Output Functions (cont'd)

Port Pin	Input/Output	Select	Connected Signal(s)	From/to Module
P0.2	Input	GPI	P0_DATA.P2	
		INP1	CCPOS2_1	CCU6
		INP2	T2EUDA	GPT12T2
		INP3	MTSR_1	SSC1
		INP4	T21EX_0	Timer 21
		INP5	T6INA	GPT12T6
	Output	GPO	P0_DATA.P2	–
		ALT1	COU60_0	CCU6
		ALT2	MTSR_1	SSC1
		ALT3	EXF2_0	Timer 2
P0.3	Input	GPI	P0_DATA.P3	
		INP1	SCK_1	SSC1
		INP2	CAPINB	GPT12
		INP3	T5INA	GPT12T5
		INP4	T4EUDA	GPT12T4
		INP5	CCPOS0_1	CCU6
	Output	GPO	P0_DATA.P3	
		ALT1	SCK_1	SSC1
		ALT2	EXF21_2	Timer 21
		ALT3	T6OUT	GPT12T6
P0.4	Input	GPI	P0_DATA.P4	
		INP1	MRST_1_0	SSC1
		INP2	CC60_0	CCU6
		INP3	T21_2	Timer 21
		INP4	EXINT2_2	SCU
		INP5	T3EUDA	GPT12T3
		INP6	CCPOS1_1	CCU6
	Output	GPO	P0_DATA.P4	
		ALT1	MRST_1_0	SSC1
		ALT2	CC60_0	CCU6
		ALT3	CLKOUT_0	SCU

14.3.3 Port 2

14.3.3.1 Port 2 Functions

Table 10 Port 2 Input Functions

Port Pin	Input/Output	Select	Connected Signal(s)	From/to Module
P2.0	Input	GPI	P2_DATA.P0	
		INP1	CCPOS0_3	CCU6
		INP2	-	-
		INP3	T12HR_2	CCU6
		INP4	EXINT0_0	SCU
		INP5	CC61_2	CCU6
		ANALOG	AN0	ADC
			XTAL (in)	XTAL
P2.2	Input	GPI	P2_DATA.P2	
		INP1	CCPOS2_3	CCU6
		INP2	T13HR_2	CCU6
		INP3	-	
		INP4	CC62_2	CCU6
		ANALOG	AN2	ADC
		OUT	XTAL (out)	XTAL
P2.3	Input	GPI	P2_DATA.P3	
		INP1	CCPOS1_0	CCU6
		INP2	CTRAP#_1	CCU6
		INP3	T21EX_2	Timer 21
		INP4	CC60_1	CCU6
		INP5	EXINT0_3	SCU
		ANALOG	AN3	ADC
P2.4	Input	GPI	P2_DATA.P4	
		INP1	CTRAP#_0	CCU6
		INP2	T2EUDB	GPT12T2
		INP3	MRST_1_1	SSC1
		INP4	EXINT1_3	SCU
		ANALOG	AN4	ADC
P2.5	Input	GPI	P2_DATA.P5	
		INP1	RXD2_1	UART2
		INP2	T3EUDB	GPT12T3
		INP3	MRST_2_1	SSC2
		INP4	T2_1	Timer 2
		ANALOG	AN5	ADC

Table 12 Timer3 Modes (cont'd)

Mode	Sub-Mode	Operation
2	No Sub-Mode	8-bit Timer with auto-reload The timer register TL3 is reloaded with a user-defined 8-bit value in TH3 upon overflow.
3	a	Timer3 operates as two 8-bit timers The timer registers TL3 and TH3, operate as two separate 8-bit counters.
3	b	Timer3 operates as Two 8-bit timers for clock measurement The timer registers, TL3 and TH3 operate as two separate 8-bit counters. In this mode the LP_CLK2 Low Power Clock can be measured. TL3 acts as an edge counter for the clock edges and TH3 as a counter which counts the time between the edges.

18 Capture/Compare Unit 6 (CCU6)

18.1 Feature Set Overview

This section gives an overview over the different building blocks and their main features.

Timer 12 Block Features

- Three capture/compare channels, each channel can be used either as capture or as compare channel
- Generation of a three-phase PWM supported (six outputs, individual signals for high-side and low-side switches)
- 16-bit resolution, maximum count frequency = peripheral clock
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of T12 registers
- Center-aligned and edge-aligned PWM can be generated
- Single-shot mode supported
- Start can be controlled by external events
- Capability of counting external events
- Multiple interrupt request sources
- Hysteresis-like control mode

Timer 13 Block Features

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock
- Concurrent update of T13 registers
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Single-shot mode supported
- Start can be controlled by external events
- Capability of counting external events

Additional Specific Functions

- Block commutation for brushless DC-drives implemented
- Position detection via hall-sensor pattern
- Noise filter supported for position input signals
- Automatic rotational speed measurement and commutation control for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ($\overline{\text{CTRAP}}$)
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage

18.2 Introduction

The CCU6 unit is made up of a Timer T12 block with three capture/compare channels and a Timer T13 block with one compare channel. The T12 channels can independently generate PWM signals or accept capture triggers, or they can jointly generate control signal patterns to drive DC-motors or inverters.

A rich set of status bits, synchronized updating of parameter values via shadow registers, and flexible generation of interrupt request signals provide efficient software-control.

29 Electrical Characteristics

This chapter includes all relevant electrical characteristics of the product TLE9879QXA20.

29.1 General Characteristics

29.1.1 Absolute Maximum Ratings

Table 17 Absolute Maximum Ratings¹⁾

$T_j = -40\text{ °C}$ to $+150\text{ °C}$, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note / Test Condition	Number
		Min.	Typ.	Max.			
Voltages – Supply Pins							
Supply voltage – VS	V_S	-0.3	–	40	V	Load dump	P_1.1.1
Supply voltage – VSD	V_{SD}	-0.3	–	48	V	–	P_1.1.2
Supply voltage – VSD	$V_{SD_max_extend}$	-2.8	–	48	V	Series resistor $R_{VSD} = 2.2\ \Omega$, $t = 8\text{ ms}$ ²⁾	P_1.1.32
Voltage range – VDDP	V_{DDP}	-0.3	–	5.5	V	–	P_1.1.3
Voltage range – VDDP	$V_{DDP_max_extend}$	-0.3	–	7	V	In case of voltage transients on V_S with $dV_S/dt \geq 1\text{V}/\mu\text{s}$; duration: $t \leq 150\mu\text{s}$; $C_{VDDP} \leq 570\text{ nF}$	P_1.1.41
Voltage range – VDDEXT	V_{DDEXT}	-0.3	–	5.5	V	–	P_1.1.4
Voltage range – VDDEXT	$V_{DDEXT_max_extend}$	-0.3	–	7	V	In case of voltage transients on V_S with $dV_S/dt \geq 1\text{V}/\mu\text{s}$; duration: $t \leq 150\mu\text{s}$; $C_{VDDEXT} \leq 570\text{ nF}$	P_1.1.42
Voltage range – VDDC	V_{DDC}	-0.3	–	1.6	V	–	P_1.1.5
Voltages – High Voltage Pins							
Input voltage at LIN	V_{LIN}	-28	–	40	V	–	P_1.1.7
Input voltage at MON	$V_{MON_maxrate}$	-28	–	40	V	³⁾	P_1.1.8
Input voltage at VDH	$V_{VDH_maxrate}$	-2.8	–	40	V	⁴⁾	P_1.1.38
Voltage range at GHx	V_{GH}	-8.0	–	48	V	⁵⁾	P_1.1.9
Voltage range at GHx vs. SHx	V_{GHvsSH}	14	–	–	V	–	P_1.1.44
Voltage range at SHx	V_{SH}	-8.0	–	48	V	–	P_1.1.11
Voltage range at GLx	V_{GL}	-8.0	–	48	V	⁶⁾ –	P_1.1.13
Voltage range at GLx vs. SL	V_{GLvsSL}	14	–	–	V	–	P_1.1.45

29.1.2 Functional Range
Table 18 Functional Range

$T_j = -40\text{ °C}$ to $+150\text{ °C}$, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note / Test Condition	Number
		Min.	Typ.	Max.			
Supply voltage in Active Mode	V_{S_AM}	5.5	–	28	V	–	P_1.2.1
Extended supply voltage in Active Mode	$V_{S_AM_extended}$	28	–	40	V	¹⁾ Functional with parameter deviation	P_1.2.16
Supply voltage in Active Mode for MOSFET Driver Supply	V_{SD_AM}	5.4	–	28	V		P_1.2.18
Extended supply voltage in Active Mode for MOSFET Driver Supply	$V_{SD_AM_extended}$	28	–	32	V	¹⁾³⁾ Functional with parameter deviation	P_1.2.17
Specified supply voltage for LIN Transceiver	$V_{S_AM_LIN}$	5.5	–	18	V	Parameter Specification	P_1.2.2
Extended supply voltage for LIN Transceiver	$V_{S_AM_LIN}$	4.8	–	28	V	Functional with parameter deviation	P_1.2.14
Supply voltage in Active Mode with reduced functionality (Microcontroller / Flash with full operation)	V_{S_AMmin}	3.0	–	5.5	V	²⁾	P_1.2.3
Supply voltage in Sleep Mode	V_{S_Sleep}	3.0	–	28	V	–	P_1.2.4
Supply voltage transients slew rate	dV_S/dt	-1	–	1	V/ μ s	³⁾	P_1.2.5
Output sum current for all GPIO pins	$I_{GPIO,sum}$	-50	–	50	mA	³⁾	P_1.2.7
Operating frequency	f_{sys}	5	–	24	MHz	⁴⁾	P_1.2.15
Junction temperature	T_j	-40	–	150	°C	–	P_1.2.9

1) This operation voltage range is only allowed for a short duration: $t_{max} \leq 400\text{ ms}$ (continuous operation at this voltage is not allowed), $f_{sys} = 24\text{ MHz}$, $I_{VDDP} = 10\text{ mA}$, $I_{VDDEXT} = 5\text{ mA}$. In addition, the power dissipation caused by the Charge Pump + MOSFET driver have to be considered.

2) Reduced functionality (e.g. cranking pulse) - Parameter deviation possible.

3) Not subject to production test, specified by design.

4) Function not specified when limits are exceeded.

29.2.4 VPRE Voltage Regulator (PMU Subblock) Parameters

The PMU VPRE Regulator acts as a supply of VDDP and VDDEXT voltage regulators.

Table 25 Functional Range

Parameter	Symbol	Values			Unit	Note / Test Condition	Number
		Min.	Typ.	Max.			
Specified output current	I_{VPRE}	–	–	110	mA	1)	P_2.4.1

1) Not subject to production test, specified by design.

29.2.4.1 Load Sharing Scenarios of VPRE Regulator

The figure below shows the possible load sharing scenarios of VPRE regulator.

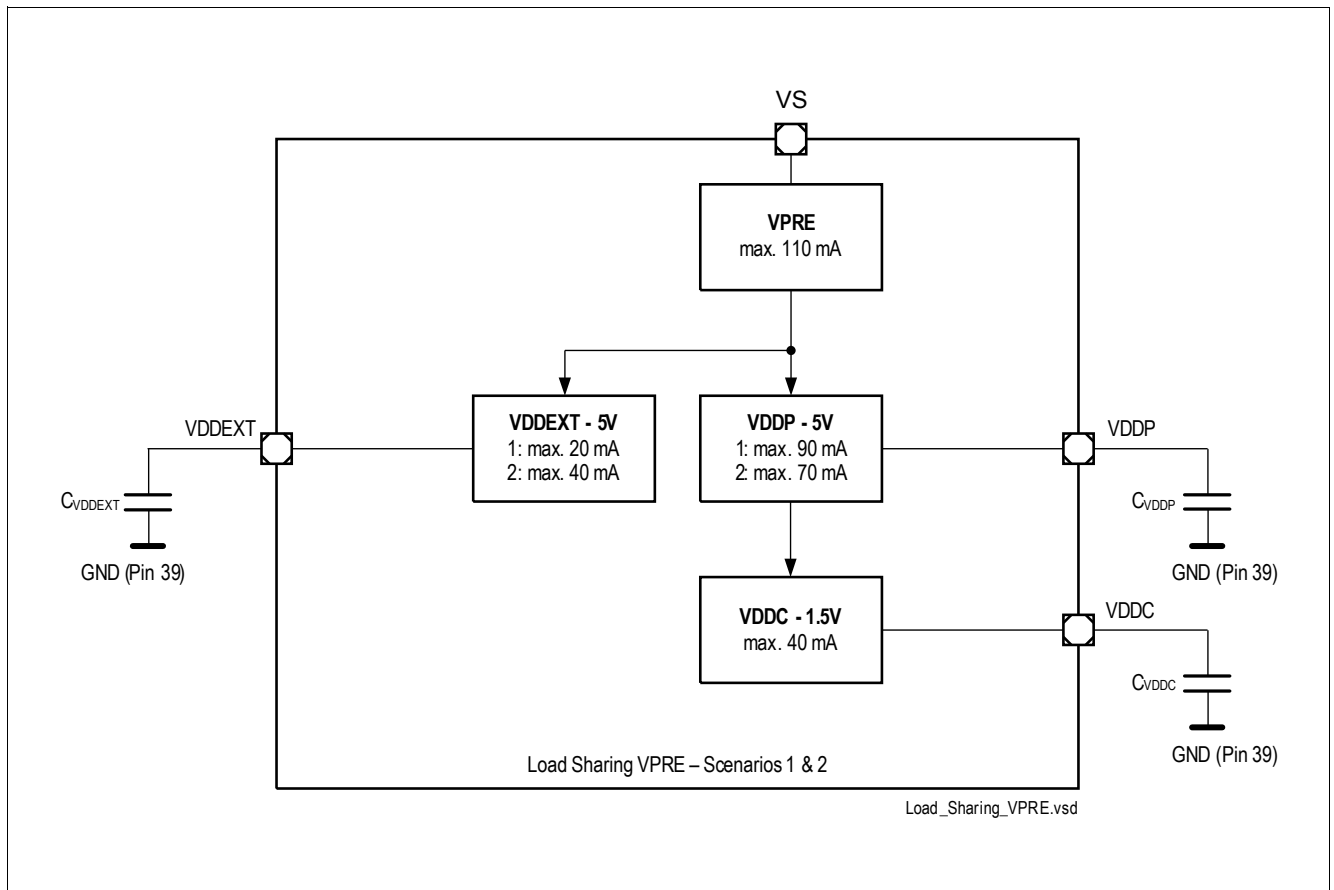


Figure 33 Load Sharing Scenarios of VPRE Regulator

29.2.5 Power Down Voltage Regulator (PMU Subblock) Parameters

The PMU Power Down voltage regulator consists of two subblocks:

- Power Down Pre regulator: VDD5VPD
- Power Down Core regulator: VDD1V5_PD (Supply used for GPUDATAx registers)

Both regulators are used as purely internal supplies. The following table contains all relevant parameters:

Table 26 Functional Range

Parameter	Symbol	Values			Unit	Note / Test Condition	Number
		Min.	Typ.	Max.			
VDD1V5_PD							
Power-On Reset Threshold	$V_{DD1V5_PD_RSTTH}$	1.2	–	1.5	V	¹⁾	P_2.5.1

1) Not subject to production test, specified by design

Electrical Characteristics
Table 42 Electrical Characteristics MOSFET Driver (cont'd)
 $V_S = 5.5 \text{ V to } 28 \text{ V}$, $T_j = -40 \text{ }^\circ\text{C to } +150 \text{ }^\circ\text{C}$, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note / Test Condition	Number
		Min.	Typ.	Max.			
Resistor between SHx and GND	R_{SHGN}	30	40	50	k Ω	¹⁾³⁾ This resistance is the resistance between GHx and GND connected through a diode to SHx. As a consequence, the voltage at SHx can rise up to 0,6V typ. before it is discharged through the resistor.	P_12.1.10
Low RDSON mode (boosted discharge mode)	R_{ONCCP}	–	9	12	Ω	$V_{VSD} = 13.5 \text{ V}$, $V_{VCP} = V_{VSD} + 14.0 \text{ V}$; $I_{CHARGE} = I_{DISCHG} = 31(\text{max})$; 50mA forced into Gx, Sx grounded	P_12.1.50
Resistance between VDH and VSD	I_{BSH}	–	4	–	k Ω	¹⁾	P_12.1.24
Input propagation time (LS on)	$t_{P(ILN)\text{min}}$	–	1.5	3	μs	¹⁾ $C_{Load} = 10 \text{ nF}$, $I_{Charge} = 3(\text{min})$, 25% of V_{Gxx1}	P_12.1.37
Input propagation time (LS off)	$t_{P(ILF)\text{min}}$	–	1.5	3	μs	¹⁾ $C_{Load} = 10 \text{ nF}$, $I_{Discharge} = 3(\text{min})$, 75% of V_{Gxx1}	P_12.1.38
Input propagation time (HS on)	$t_{P(IHN)\text{min}}$	–	1.5	3	μs	¹⁾ $C_{Load} = 10 \text{ nF}$, $I_{Charge} = 3(\text{min})$ 25% of V_{Gxx1}	P_12.1.39
Input propagation time (HS off)	$t_{P(IHF)\text{min}}$	–	1.5	3	μs	¹⁾ $C_{Load} = 10 \text{ nF}$, $I_{Discharge} = 3(\text{min})$, 75% of V_{Gxx1}	P_12.1.40
Input propagation time (LS on)	$t_{P(ILN)\text{max}}$	–	200	350	ns	$C_{Load} = 10 \text{ nF}$, $I_{Charge} = 31(\text{max})$, 25% of V_{Gxx1}	P_12.1.26
Input propagation time (LS off)	$t_{P(ILF)\text{max}}$	–	200	300	ns	$C_{Load} = 10 \text{ nF}$, $I_{Discharge} = 31(\text{max})$, 75% of V_{Gxx1}	P_12.1.27
Input propagation time (HS on)	$t_{P(IHN)\text{max}}$	–	200	350	ns	$C_{Load} = 10 \text{ nF}$, $I_{Charge} = 31(\text{max})$, 25% of V_{Gxx1}	P_12.1.28
Input propagation time (HS off)	$t_{P(IHF)\text{max}}$	–	200	300	ns	$C_{Load} = 10 \text{ nF}$, $I_{Discharge} = 31(\text{max})$, 75% of V_{Gxx1}	P_12.1.29

Trademarks of Infineon Technologies AG

μ HVIC™, μ IPM™, μ PFC™, AU-ConvertIR™, AURIX™, C166™, CanPAK™, CIPOS™, CIPURSE™, CoolDP™, CoolGaN™, COOLiR™, CoolMOS™, CoolSET™, CoolSiC™, DAVE™, DI-POL™, DirectFET™, DrBlade™, EasyPIM™, EconoBRIDGE™, EconoDUAL™, EconoPACK™, EconoPIM™, EiceDRIVER™, eupec™, FCOS™, GaNpowIR™, HEXFET™, HITFET™, HybridPACK™, iMOTION™, IRAM™, ISOFACE™, IsoPACK™, LEDriviR™, LITIX™, MIPAQ™, ModSTACK™, my-d™, NovalithIC™, OPTIGA™, OptiMOS™, ORIGA™, PowIRaudio™, PowIRstage™, PrimePACK™, PrimeSTACK™, PROFET™, PRO-SIL™, RASIC™, REAL3™, SmartLEWIS™, SOLID FLASH™, SPOC™, StrongIRFET™, SupIRBuck™, TEMPFET™, TRENCHSTOP™, TriCore™, UHVIC™, XHP™, XMC™.

Trademarks updated November 2015

Other Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Edition 2017-03-03

Published by

Infineon Technologies AG

81726 Munich, Germany

© 2017 Infineon Technologies AG.

All Rights Reserved.

Do you have a question about any aspect of this document?

Email: erratum@infineon.com

IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.